

PSM10065H

650V 10A 400mΩ Si Super junction MOSFET with Normal body diode



Features

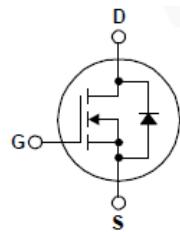
Si Super junction MOSFET

- Rated to 650V at 10Amps @ $T_J = 25^\circ\text{C}$
- Max $R_{DS(on)} = 400 \text{ m}\Omega$
- Typ $R_{DS(on)} = 380 \text{ m}\Omega$
- Gate Charge(Typ. $Q_g=20 \text{ nC}$)
- Improved dv/dt Capability
- 100% Avalanche Tested



Application

- LCD/LED/PDP TV
- Telecom/Server Power supplies
- AC-DC Power Supply
- LED Lighting



PKG type : TO-220F

Description

PSM10065H is PowerCubeSemi's second generation of high voltage Super Junction MOSFET that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, the combination of Super Junction MOSFET is suitable for various AC/DC power conversion for system miniaturization and higher efficiency

Absolute Maximum Ratings

| Symbol | Parameter | Test Condition | Value | Unit |
|------------|--------------------------------|--------------------------------------------------------------------------|------------|------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0\text{V}, I_D=250\mu\text{A}$ | 650 | V |
| I_D | Drain Current | $T_c=25^\circ\text{C}$ | 10 | A |
| I_{DM} | Pulsed Drain Current | Pulse width limited by junction temperature | 20 | A |
| V_{GS} | Gate-Source Voltage | | ± 30 | V |
| E_{AS} | Single Pulsed Avalanche Energy | $I_{AS}=4.5\text{A}, R_G=25\Omega$ $V_{DD}=50\text{V}, L=20\text{mH}$ | 170 | mJ |
| P_d | Power Dissipation | $T_c=25^\circ\text{C}$ | 89.2 | W |
| T_J | Operating Junction Temperature | | 150 | °C |
| T_{stg} | Storage Temperature | | -55 to 150 | °C |



Package Marking and Ordering Information

| Device Marking | Device | Package | Packing Method | Tape width | Quantity |
|----------------|----------|---------|----------------|------------|----------|
| PSM10065H | PSM10065 | TO-220F | Tube | - | 50 unit |

Electrical Characteristics of Si MOSFET

| Symbol | Parameter | Test Condition | Numerical | | | Unit |
|--------------|-----------------------------------------|------------------------------------------------------------|-----------|------|----------|-----------|
| | | | Min | Typ. | Max. | |
| BV_{DSS} | Drain-source breakdown voltage | $V_{GS} = 0V, I_D = 1mA, T_J = 25^\circ C$ | 650 | - | - | V |
| I_{DSS} | Zero gate voltage drain current | $V_{DS} = 650V, V_{GS} = 0V$ | - | - | 30 | μA |
| I_{GSS} | Gate-source leakage current | $V_{GS} = \pm 30V, V_{DS} = 0V$ | - | - | ± 70 | nA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 3 | - | 5 | V |
| $R_{DS(ON)}$ | Static drain-source on state resistance | $V_{GS} = 10V, I_D = 10A$ | - | 380 | 400 | $m\Omega$ |
| $t_{d(on)}$ | Turn-on Delay time | $V_{DD} = 380 V, I_D = 5A, V_{GS} = 10 V, R_G = 4.7\Omega$ | - | 15 | - | ns |
| T_r | Turn-on Rise time | | - | 9 | - | |
| $t_{d(off)}$ | Turn-off Delay time | | - | 59 | - | |
| T_f | Turn-off Fall time | | - | 10 | - | |



Electrical Characteristics of Si MOSFET

| Symbol | Parameter | Test Condition | Numerical | | Unit |
|-----------------|--------------------------------------|--------------------------------------------------------------------|-----------|------|------|
| | | | Typ. | Max. | |
| $R_{\theta JC}$ | Thermal resistance, Junction to case | | 1.4 | - | °C/W |
| R_g | Gate resistance | $V_{GS} = 0V, f = 100kHz$ | 8 | 10 | Ω |
| C_{iss} | Input capacitance | $V_{DS} = 200V, V_{GS} = 0V, f = 1MHz$ | 1000 | - | pF |
| C_{oss} | Output capacitance | | 30 | - | |
| C_{rss} | Reverse transfer capacitance | | 2 | - | |
| $Q_{g(tot)}$ | Total gate charge at 10V | $V_{DS} = 520V, I_D = 10A$ $V_{GS(on)} = 10V, V_{GS(off)} = 0V$ | 20 | - | nC |
| Q_{gs} | Gate to source gate charge | | 5 | - | |
| Q_{gd} | Gate to drain "Miller" charge | | 10 | - | |

Electrical Characteristics of Si Diode

| Symbol | Parameter | Test Condition | Numerical | | Unit |
|-----------|----------------------------------------------------------|----------------------------------------------------|-----------|------|------|
| | | | Typ. | Max. | |
| I_S | Maximum continuous drain to source diode forward current | | - | 10 | A |
| I_{SM} | Maximum pulsed drain to source diode forward current | | - | 20 | A |
| V_{SD} | Drain to source diode forward voltage | $I_{SD} = 10A, V_{GS} = 0V$ | - | 1.1 | V |
| T_{rr} | Reverse recovery time | $I_{SD} = 5A, V_{DD} = 400V, dI_F/dt = 100A/\mu s$ | 265 | - | ns |
| Q_{rr} | Reverse recovery charge | | 2.9 | - | μC |
| I_{rrm} | Reverse recovery current | | 22 | - | A |

Typical Characteristics

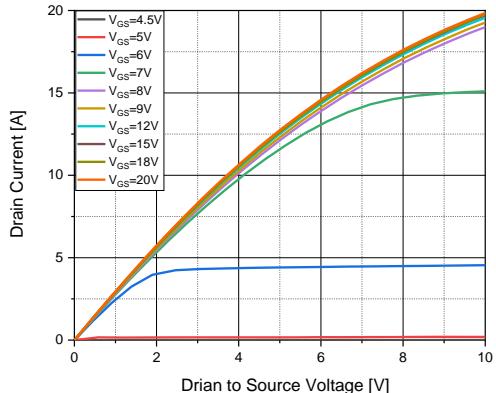


Figure 1. On-state characteristics

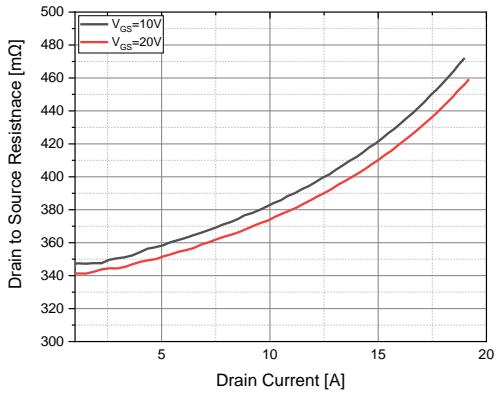


Figure 2. On resistance variation vs Drain current and gate voltage

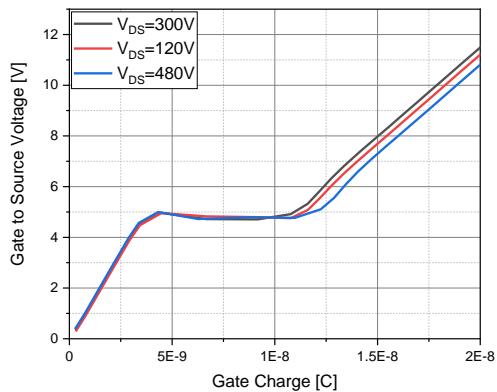


Figure 3. Gate charge characteristics

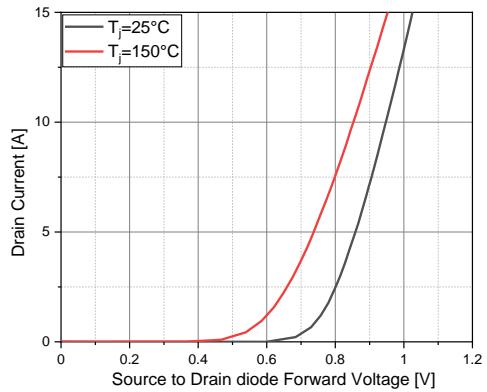


Figure 4. On-state current vs Diode forward voltage

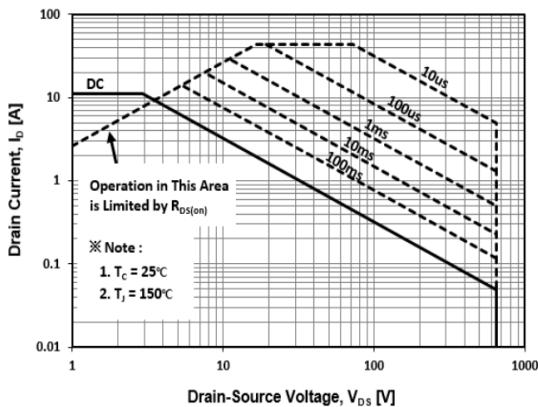


Figure 5. Maximum safe operating area

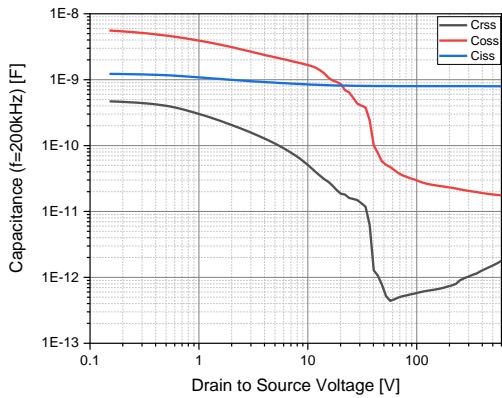


Figure 6. Capacitance characteristics

Typical Characteristics

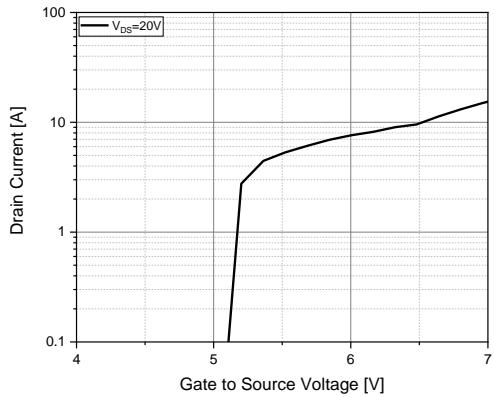


Figure 7. Transfer characteristics

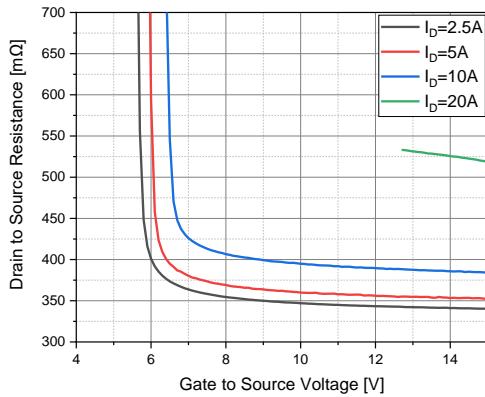


Figure 8. Drain to source resistance vs Gate to source voltage

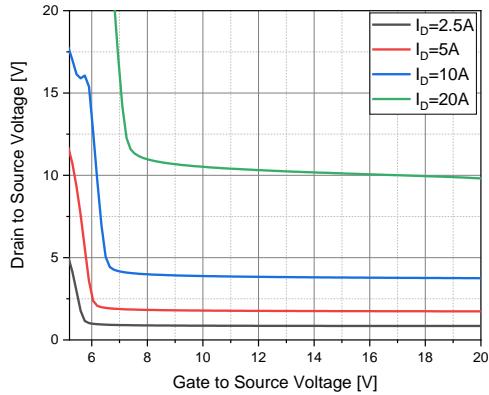


Figure 9. Drain to source voltage vs Gate to Source voltage

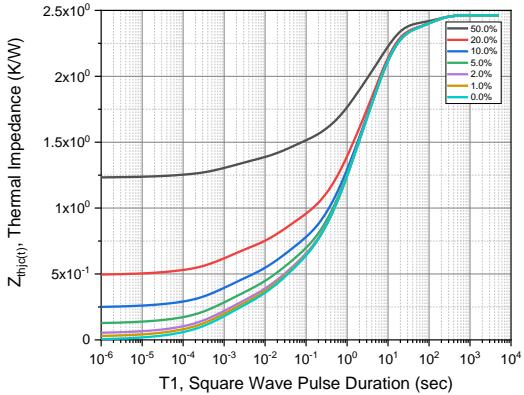
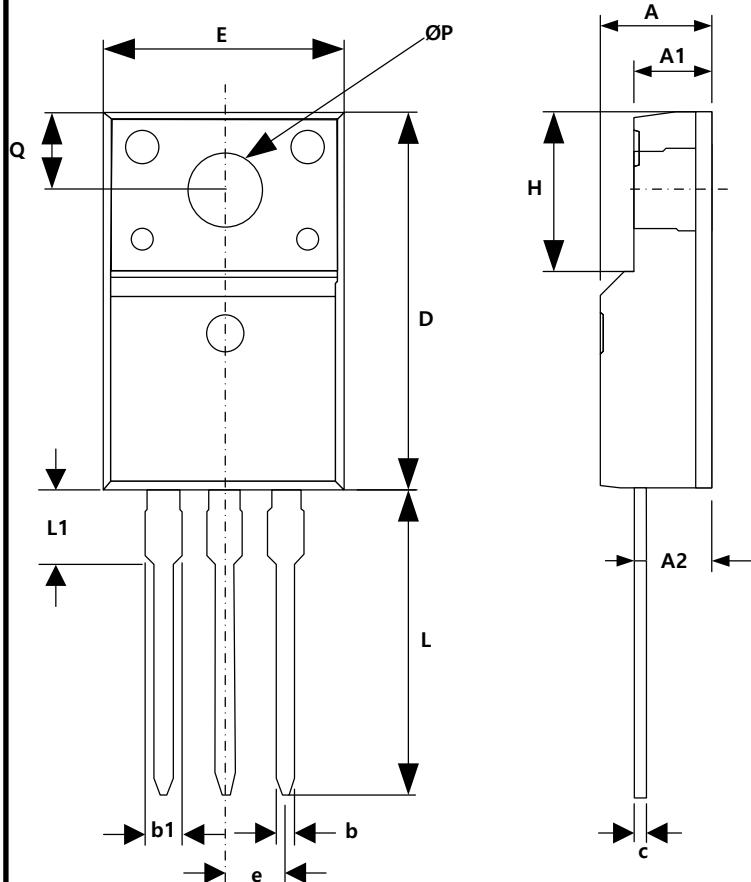


Figure 10. Transient thermal response curve



Package Outline



| SYMBOL | DIMENSIONS | | NOTES |
|--------|------------|-------|-------|
| | MIN | MAX | |
| A | 4.50 | 4.90 | |
| A1 | 2.34 | 2.74 | |
| A2 | 2.56 | 2.96 | |
| b | 0.70 | 0.90 | |
| b1 | 1.27 | 1.47 | |
| c | 0.45 | 0.60 | |
| D | 15.67 | 16.07 | |
| E | 9.96 | 10.36 | |
| e | 2.54 BSC | | |
| H | 6.48 | 6.88 | |
| L | 12.68 | 13.28 | |
| L1 | 3.03 | 3.43 | |
| ØP | 3.08 | 3.28 | |
| Q | 3.20 | 3.40 | |

